



Initial Product/Process Change Notification  
 Document #:IPC25374X  
 Issue Date:11 Oct 2023

<b>Title of Change:</b>	Galvanic Isolation Process 2nd source from "Gresham" to "Gresham or Aizu"	
<b>Proposed First Ship date:</b>	04 Nov 2024 or earlier if approved by customer	
<b>Contact Information:</b>	Contact your local onsemi Sales Office or <a href="mailto:Joswald.Macabale@onsemi.com">Joswald.Macabale@onsemi.com</a>	
<b>PCN Samples Contact:</b>	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
<b>Type of Notification:</b>	This is an Initial Product/Process Change Notification (IPC2N) sent to customers. An IPC2N is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPC2N). This IPC2N notification will be followed by a Final Product/Process Change Notification (FPC2N) at least 90 days prior to implementation of the change. In case of questions, contact < <a href="mailto:PCN.Support@onsemi.com">PCN.Support@onsemi.com</a> >	
<b>Marking of Parts/ Traceability of Change:</b>	Product that is produced out of onsemi Aizu, Japan can be identified on the label by referring to the "Diffused In" location. If produced out of onsemi Aizu, Japan, it will show JP. If it is produced out of onsemi Gresham, US, it will show US.	
<b>Change Category:</b>	Wafer Fab Change	
<b>Change Sub-Category(s):</b>	Manufacturing Site Addition	
<b>Sites Affected:</b>		
<b>onsemi Sites</b>	<b>External Foundry/Subcon Sites</b>	
onsemi Aizu, Japan	None	
<b>Description and Purpose:</b>		
onsemi would like to notify its customers of its intent to qualify our Isolated Gate Driver technology at our onsemi Aizu, Japan wafer FAB. The qualification enables expanded capacity for this technology. All products listed in this IPC2N , upon completion of qualification and the FPC2N, may be dual sourced from either the current onsemi wafer FAB at onsemi Gresham, US or onsemi Aizu, Japan.		
	<b>From</b>	<b>To</b>
<b>Fab Site</b>	onsemi, Gresham US	onsemi, Aizu Japan or onsemi, Gresham US
There is no product marking change as a result of this change.		



**Qualification Plan:**

QV DEVICE NAME: NCV51561  
 RMS: 90767  
 PACKAGE: SOIC16 WB

Test	Specification	Condition	Interval
High Temperature Operating Life	JESD22-A108	Ta=125°C, Vcc = 1.2 x nominal	1008 hrs
Early Life Failure Rate	AECQ100-008	Ta=125°C, Vcc = 1.2 x nominal	48 hrs
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C	-
Temperature Cycling	JESD22-A104	Ta= -55°C to +125°C	1000 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
Power Temperature Cycling	JESD22-A105	Ta= -40°C to +125°C	1000 cyc

Estimated date for qualification completion: 7 May 2024

**List of Affected Parts:**

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [\*\*PCN Customized Portal\*\*](#).

Part Number	Qualification Vehicle
NCP51563CADWR2G	NCV51561BBDWR2G
NCP51563BBDWR2G	NCV51561BBDWR2G
NCP51561DBDWR2G	NCV51561BBDWR2G
NCP51561DADWR2G	NCV51561BBDWR2G
NCP51561BBDWR2G	NCV51561BBDWR2G
NCP51561BADWR2G	NCV51561BBDWR2G
NCP51560BBDWR2G	NCV51561BBDWR2G
NCP51560ABDWR2G	NCV51561BBDWR2G